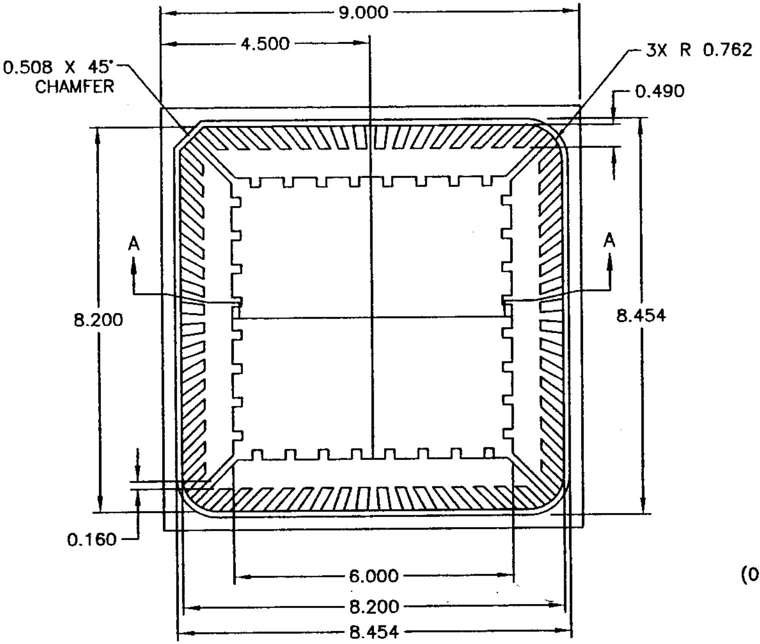
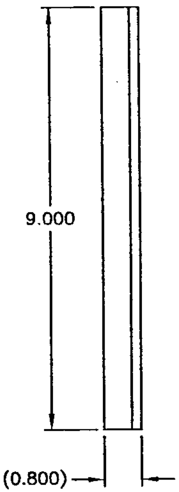
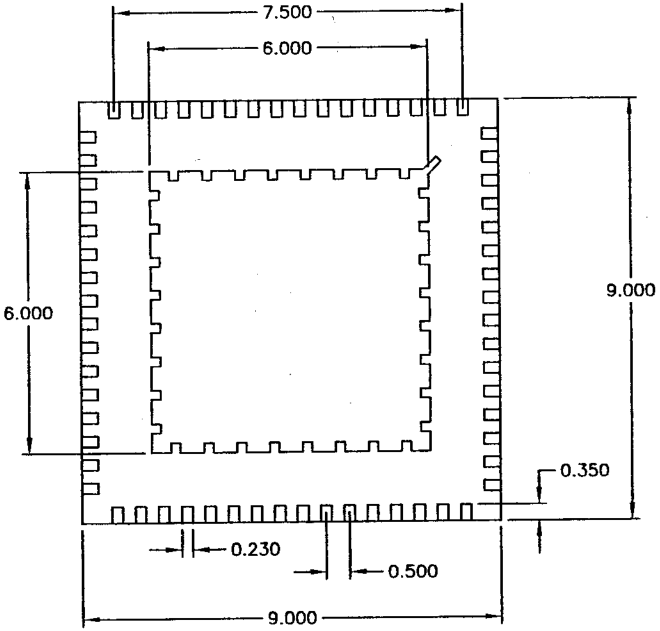
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
		PRODUCTION RELEASE	

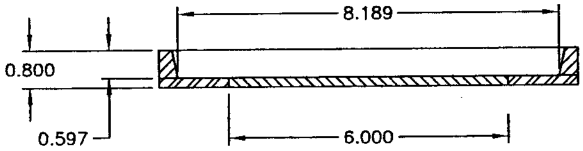


TOP VIEW





BOTTOM VIEW



SECTION A–A

NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
3. LEAD FRAME: COPPER, 194 FH.
4. LEAD FINISH: FULL GOLD PLATE.
5. FRAME THICKNESS: 0.2030 ±.0076
6. DIE PAD: 6.000 X 6.000
7. JEDEC OUTLINE: MO–220.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
X.XX ± 0.15 X.XXXX ± ---
X.XXX ± 0.100 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	DATE
APP BY	DATE
CUSTOMER	----

64 Lead 9mm x 9mm

QFN9X9–064 REV 1